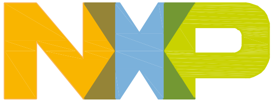

TOP VIEW

PIN A1 INDEX
CAPACITOR 6 PLACES
4X 0.2
D, B, E, C, E2, E4, D4, D2, 2X D3, 2X E3

BOTTOM VIEW

(D1), (E1), 18X e, 18X e
360X ⌀b
⌀0.3Ⓜ A B C
⌀0.15Ⓜ A
Rows: A B C D E F G H J K L M N P R T U V W
Columns: 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19

SIDE VIEW

360X 0.2 A
// 0.25 A
// 0.35 A
A, A1, A2, A3, A4

© NXP SEMICONDUCTORS N.V.
ALL RIGHTS RESERVED

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 360 I/O, FC PBGA, 25 X 25 PKG, 1.27MM PITCH	DOCUMENT NO: 98ARS23918W REV: E
	STANDARD: JEDEC MO-151 BAK-1
	SOT1636-1 04 JAN 2016

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.
3. DIMENSION b IS THE MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. D2 AND E2 DEFINE THE AREA OCCUPIED BY THE DIE AND UNDERFILL. ACTUAL SIZE OF THIS AREA MAY BE SMALLER THAN SHOWN. D3 AND E3 ARE THE MINMUM CLEARANCE FROM THE PACKAGE EDGE TO THE CHIP CAPACITORS.
5. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.
6. CAUTION MUST BE TAKEN NOT TO SHORT EXPOSED METAL CAPACITOR PADS ON PACKAGE TOP.

DIM	MIN		MAX	DIM	MIN		MAX	DIM	MIN		MAX
A	–	–	2.77	E1		22.86 REF		–	–	–	–
A1	0.5	–	0.7	E2	–	–	14.6	–	–	–	–
A2	1	–	1.2	E3	2.5	–	–	–	–	–	–
A3	–	–	0.6	E4	8.1	–	–	–	–	–	–
A4	0.82	–	0.9	–	–	–	–	–	–	–	–
b	0.6	–	0.9	–	–	–	–	–	–	–	–
D		25 BSC		–	–	–	–	–	–	–	–
D1		22.86 REF		–	–	–	–	–	–	–	–
D2	–	–	13.3	–	–	–	–	–	–	–	–
D3	2.5	–	–	–	–	–	–	–	–	–	–
D4	6.6	–	–	–	–	–	–	–	–	–	–
e		1.27 BSC		–	–	–	–	–	–	–	–
E		25 BSC		–	–	–	–	–	–	–	–

© NXP SEMICONDUCTORS N. V.
ALL RIGHTS RESERVED

MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE:

360 I/O, FC PBGA,
25 X 25 PKG, 1.27MM PITCH

DOCUMENT NO: 98ARS23918W REV: E

STANDARD: JEDEC MO–151 BAK–1

SOT1636–1 04 JAN 2016